

IN THE SPECIFICATION:

Please replace the indicated paragraphs as follows:

Paragraph beginning at page 4, line 21:

Q¹
Die 12 is preferably a one-piece item that is often referred to in the art as "bumped die." As can be seen in Figure 1A, a bumped die includes die 12, "under bump material" that serves as an intermediated layer 26 between the top surface of the die and solder bump 22, and the solder bumps themselves. Preferably, the under bump material is one of TiW, Cu, Au or an equivalent. In the example illustrated in Figure 1A, the under bump material is broken into three layers-Cu plating 26a, sputtered Cu 26b and sputtered Ti 26c.